HMC400MS8

HIGH IP3 GaAs MMIC MIXER, 1.7 - 2.2 GHz

Typical Applications

High Dynamic Range Infrastructure:

- GSM, GPRS & EDGE
- CDMA & W-CDMA
- Cable Modem Termination Systems

Features

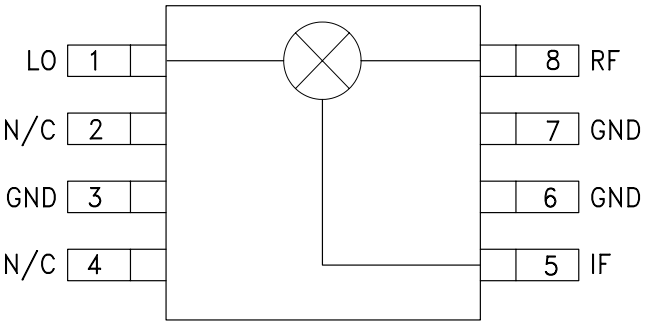
+35 dBm Input IP3

Conversion Loss: 8.8 dB

No External Components

Ultra Small MSOP Package: 14.8mm^2

Functional Diagram



General Description

The HMC400MS8 is a high dynamic range passive MMIC mixer in a plastic surface mount 8 lead Mini Small Outline Package (MSOP) covering 1.7 to 2.2 GHz. Excellent input IP3 performance of +36 dBm for down conversion and +29 dBm for up conversion is provided for 2.5G & 3G GSM/CDMA based UMTS or PCS applications at an LO drive of +17dBm. With a 1dB compression of +21 dBm, the RF port will accept a wide range of input signal levels. Conversion loss is 8.5dB typical and LO isolations are maintained at 22 to 33 dB. This miniature single-ended monolithic GaAs FET mixer does not require any external components or bias. The 50 to 300 MHz IF frequency response will satisfy many UMTS/PCS transmit or receive frequency plans configured for low side LO. The HMC400MS8 input IP3 performance coupled with its high P1dB rivals traditional active FET mixers while offering a much smaller 14.8mm^2 standard IC footprint and no DC bias.

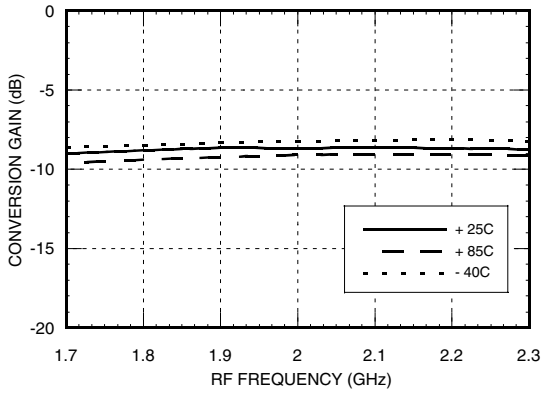
Electrical Specifications, T_A = +25°C, LO = +17dBm, IF = 200 MHz*

Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range, RF	1.7 - 1.8			1.8 - 2.0			2.0 - 2.2			GHz
Frequency Range, LO	1.4 - 1.75			1.5 - 1.95			1.7 - 2.15			GHz
Frequency Range, IF	DC - 300			DC - 300			DC - 300			MHz
Conversion Loss		9	11		8.8	10.5		8.8	10.5	dB
Noise Figure (SSB)		9	11		8.8	10.5		8.8	10.5	dB
LO to RF Isolation	29	33		24	30		20	25		dB
LO to IF Isolation	16	20		17	22		19	25		dB
IP3 (Input)	30	34		32	36		28	32		dBm
1 dB Gain Compression (Input)	18	21		18	21		18	22		dBm
LO Input Drive Level (Typical)	+16 to +18			+16 to +18			+16 to +18			dBm

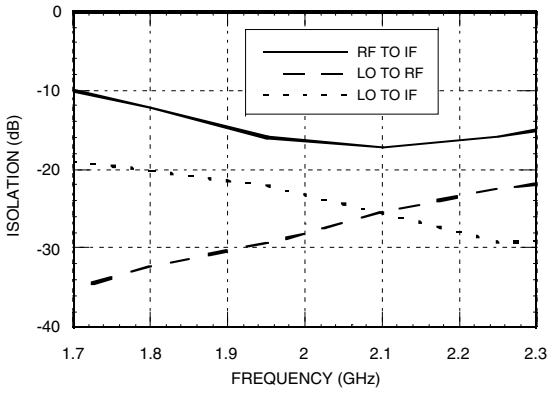
Unless otherwise noted, all measurements performed as a downconverter, with low side LO & IF = 200 MHz.

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
12 Elizabeth Drive, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order Online at www.hittite.com

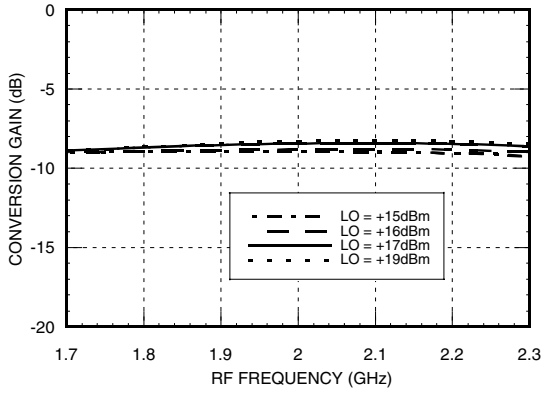
Conversion Gain vs. Temperature @ LO = +17 dBm



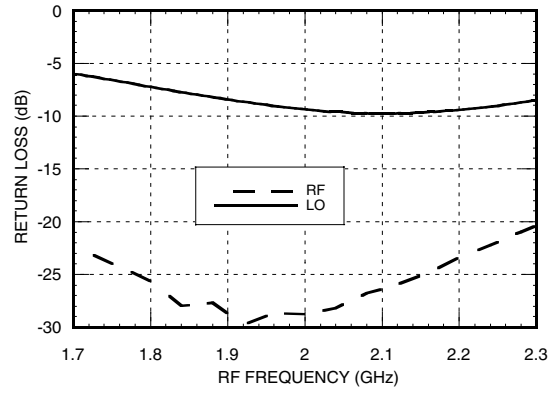
Isolation @ LO = +17 dBm



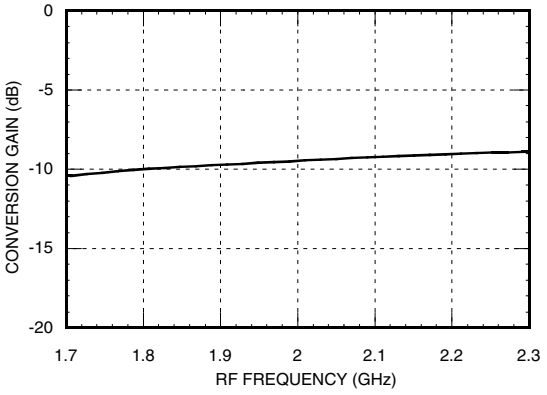
Conversion Gain vs. LO Drive



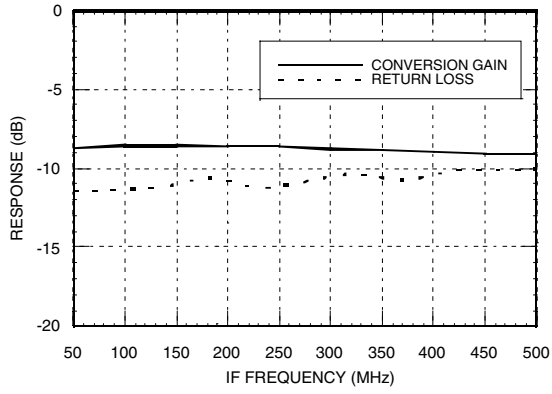
Return Loss @ LO = +17 dBm



Upconverter Performance Conversion Gain @ LO = +17 dBm

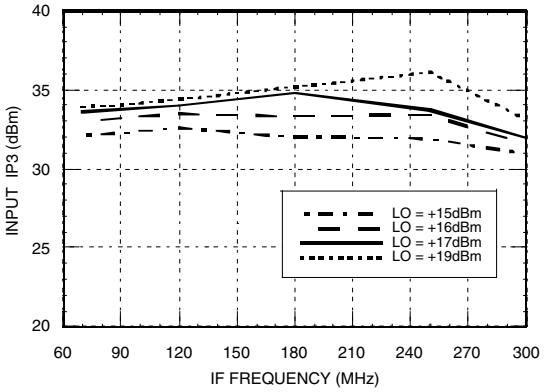


If Bandwidth @ LO = +17 dBm

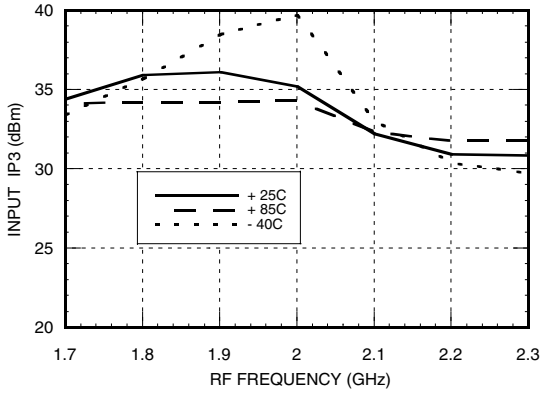


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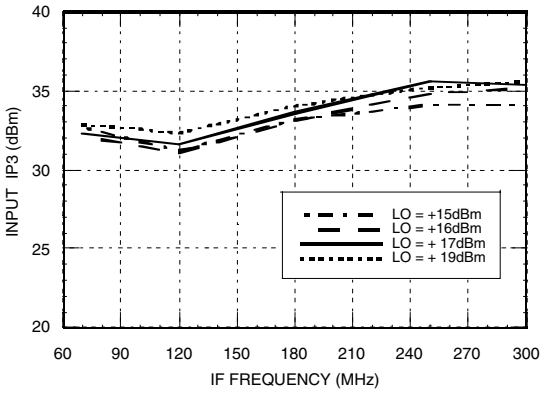
Input IP3 vs. IF Frequency, RF = 1.75 GHz



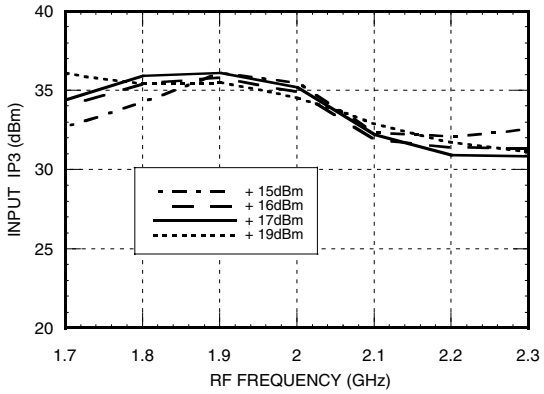
Input IP3 vs. Temperature, LO = +17 dBm



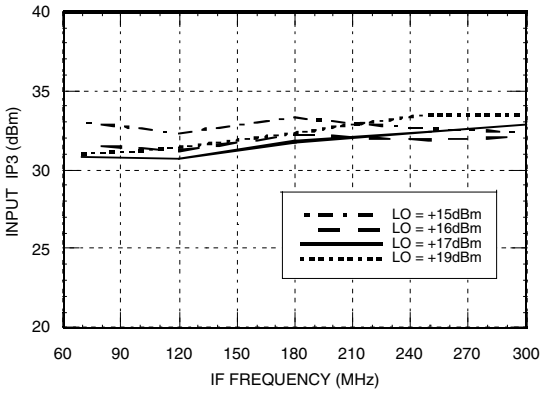
Input IP3 vs. IF Frequency, RF = 1.95 GHz



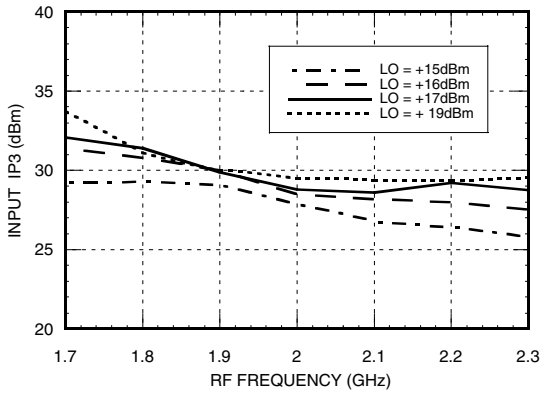
Input IP3 vs. LO Drive



Input IP3 vs. IF Frequency, RF = 2.15 GHz

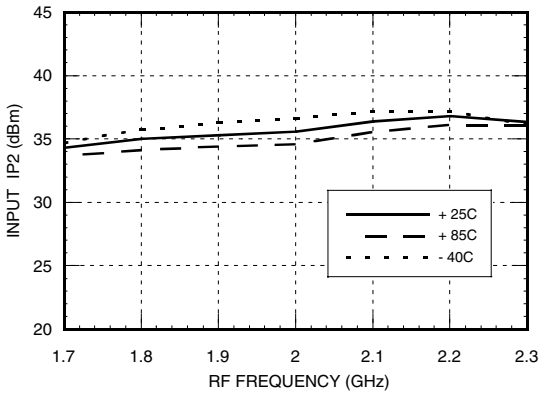


Upconverter IP3 vs. LO Drive, IF = 200 MHz

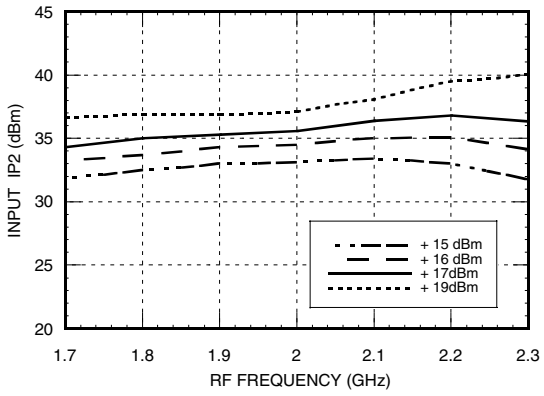


*Unless otherwise noted, all measurements performed as a downconverter, with low side LO & IF = 200 MHz.

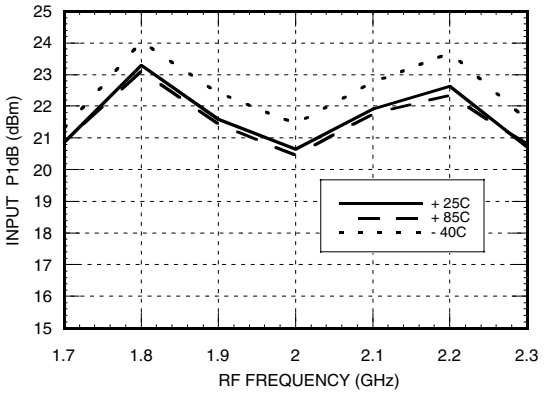
Input IP2 vs. Temperature @ LO = +17 dBm



Input IP2 vs. LO Drive @ LO = +17 dBm



Input P1dB vs. Temperature @ LO = +17 dBm



MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	xx	-11	7	4	8
1	9	0	24	31	27
2	71	70	49	58	64
3	79	80	80	79	77
4	77	80	80	79	80

RF Freq = 2 GHz @ -10 dBm
LO Freq = 1.8 GHz @ +17 dBm
All values in dBc relative to the IF output power.

Harmonics of LO

	nLO Spur @ RF Port			
LO Freq (GHz)	1	2	3	4
1.4	42	26	56	46
1.55	33	25	56	53
1.7	29	29	49	50
1.85	26	31	44	53
2	24	36	44	48
2.15	21	38	43	49

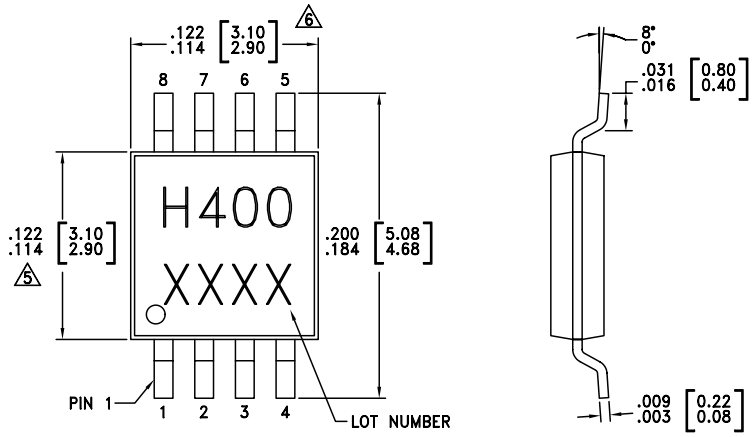
LO = +17 dBm
All values are in dBc below input LO level @ RF port.

Absolute Maximum Ratings

RF/IF Input	+27 dBm
LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
IF DC Current	±40 mA

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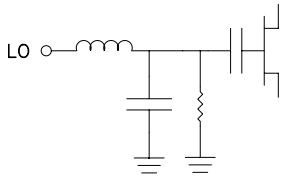
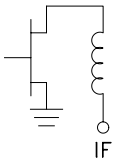
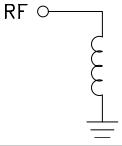
Outline Drawing



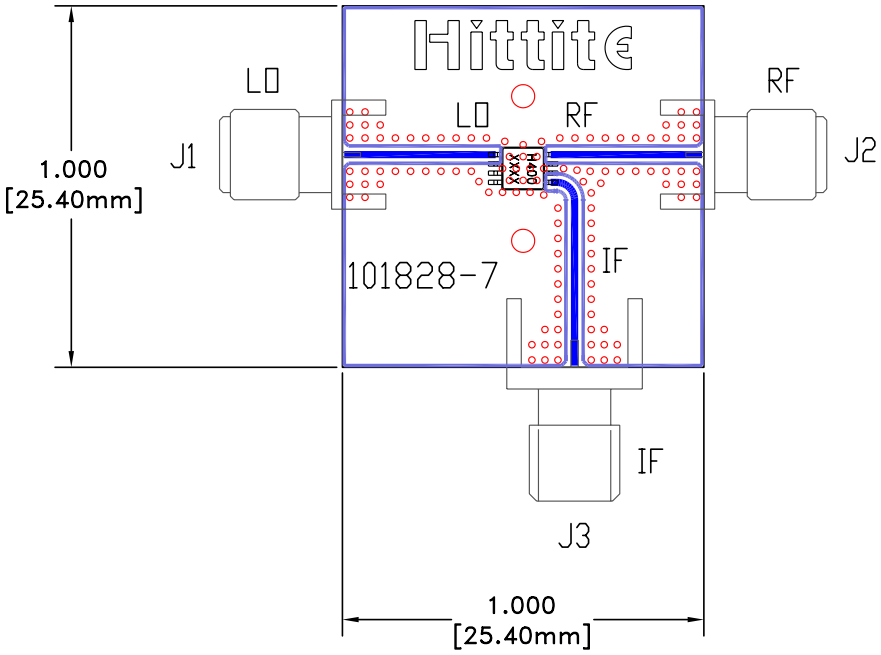
NOTES:

1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD MATERIAL: COPPER ALLOY
3 LEAD PLATING: Sn/Pb SOLDER
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
5. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
7. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO THE PCB RF GROUND

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	LO	This pin is AC coupled & matched to 50 Ohms from 1.4 to 2.2 GHz. Blocking capacitors are required if line potential is not equal to 0V.	
2, 4	N/C	Not connected.	
3, 6, 7	GND	This pin must be connected to RF ground.	
5	IF Port	This pin is DC coupled. For applications not requiring operation to DC this port should be DC blocked externally using a series capacitor. Choose value of capacitor to pass IF frequency desired. For operation to DC, this pin must not sink/source more than 40 mA of current or failure may result.	
8	RF Port	This pin is DC coupled & matched to 50 Ohm from 1.7 to 2.2 GHz	

Evaluation PCB



List of Material

Item	Description
J1 - J3	PC Mount SMA RF Connector
U1	HMC400MS8 Mixer
PCB*	101828 Eval Board
* Circuit Board Material: Rogers 4350	

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of VIA holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.